



## Material Content Data Sheet



<b>Sales Product Name</b>		SAK-XC822MT-1FRA AA		<b>Issued</b>		24. January 2018		
<b>MA#</b>		MA001604624						
<b>Package</b>		PG-TSSOP-16-1		<b>Weight*</b>		60.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.168	5.28	5.28	52756	52756
leadframe	non noble metal	nickel	7440-02-0	8.109	13.50		135045	
	non noble metal	iron	7439-89-6	11.199	18.65	32.15	186491	321536
wire	noble metal	gold	7440-57-5	0.300	0.50	0.50	5004	5004
encapsulation	organic material	carbon black	1333-86-4	0.103	0.17		1718	
	plastics	epoxy resin	-	4.366	7.27		72714	
	inorganic material	silicondioxide	60676-86-0	29.912	49.81	57.25	498122	572554
leadfinish	non noble metal	tin	7440-31-5	0.915	1.52	1.52	15234	15234
plating	noble metal	silver	7440-22-4	0.856	1.43	1.43	14261	14261
glue	plastics	acrylic resin	-	0.246	0.41		4104	
	noble metal	silver	7440-22-4	0.874	1.46	1.87	14551	18655
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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